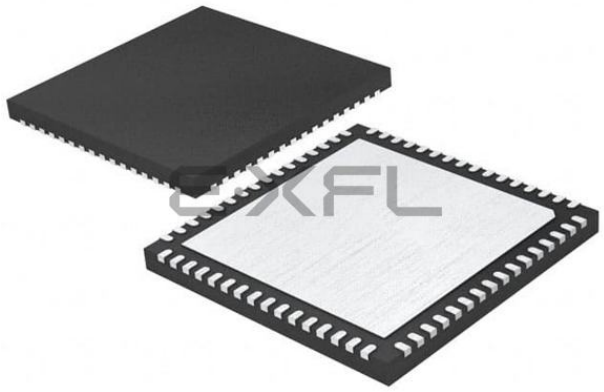
Microchip Technology - DSPIC33EP256MC506-E/MR Datasheet



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Connectivity	CANbus, I²C, IrDA, LINbus, QEI, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, DMA, Motor Control PWM, POR, PWM, WDT
Number of I/O	53
Program Memory Size	256KB (85.5K x 24)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	16K x 16
Voltage - Supply (Vcc/Vdd)	3V ~ 3.6V
Data Converters	A/D 16x10b/12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 125°C (TA)
Mounting Type	Surface Mount
Package / Case	64-VFQFN Exposed Pad
Supplier Device Package	64-VQFN (9x9)
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4.2 Data Address Space

The dsPIC33EPXXXGP50X, dsPIC33EPXXXMC20X/50X and PIC24EPXXXGP/MC20X CPU has a separate 16-bit-wide data memory space. The Data Space is accessed using separate Address Generation Units (AGUs) for read and write operations. The data memory maps, which are presented by device family and memory size, are shown in Figure 4-7 through Figure 4-16.

All Effective Addresses (EAs) in the data memory space are 16 bits wide and point to bytes within the Data Space. This arrangement gives a base Data Space address range of 64 Kbytes (32K words).

The base Data Space address is used in conjunction with a Read or Write Page register (DSRPAG or DSWPAG) to form an Extended Data Space, which has a total address range of 16 Mbytes.

dsPIC33EPXXXGP50X, dsPIC33EPXXXMC20X/50X and PIC24EPXXXGP/MC20X devices implement up to 52 Kbytes of data memory (4 Kbytes of data memory for Special Function Registers and up to 48 Kbytes of data memory for RAM). If an EA points to a location outside of this area, an all-zero word or byte is returned.

4.2.1 DATA SPACE WIDTH

The data memory space is organized in byte-addressable, 16-bit-wide blocks. Data is aligned in data memory and registers as 16-bit words, but all Data Space EAs resolve to bytes. The Least Significant Bytes (LSBs) of each word have even addresses, while the Most Significant Bytes (MSBs) have odd addresses.

4.2.2 DATA MEMORY ORGANIZATION AND ALIGNMENT

To maintain backward compatibility with PIC® MCU devices and improve Data Space memory usage efficiency, the dsPIC33EPXXXGP50X, dsPIC33EPXXXMC20X/50X and PIC24EPXXXGP/MC20X instruction set supports both word and byte operations. As a consequence of byte accessibility, all Effective Address calculations are internally scaled to step through word-aligned memory. For example, the core recognizes that Post-Modified Register Indirect Addressing mode [Ws++] results in a value of Ws + 1 for byte operations and Ws + 2 for word operations.

A data byte read, reads the complete word that contains the byte, using the LSb of any EA to determine which byte to select. The selected byte is placed onto the LSB of the data path. That is, data memory and registers are organized as two parallel, byte-wide entities with shared (word) address decode but separate write lines. Data byte writes only write to the corresponding side of the array or register that matches the byte address.

All word accesses must be aligned to an even address. Misaligned word data fetches are not supported, so care must be taken when mixing byte and word operations, or translating from 8-bit MCU code. If a misaligned read or write is attempted, an address error trap is generated. If the error occurred on a read, the instruction underway is completed. If the error occurred on a write, the instruction is executed but the write does not occur. In either case, a trap is then executed, allowing the system and/or user application to examine the machine state prior to execution of the address Fault.

All byte loads into any W register are loaded into the LSB. The MSB is not modified.

A Sign-Extend (SE) instruction is provided to allow user applications to translate 8-bit signed data to 16-bit signed values. Alternatively, for 16-bit unsigned data, user applications can clear the MSB of any W register by executing a Zero-Extend (ZE) instruction on the appropriate address.

4.2.3 SFR SPACE

The first 4 Kbytes of the Near Data Space, from 0x0000 to 0x0FFF, is primarily occupied by Special Function Registers (SFRs). These are used by the dsPIC33EPXXXGP50X, dsPIC33EPXXXMC20X/50X and PIC24EPXXXGP/MC20X core and peripheral modules for controlling the operation of the device.

SFRs are distributed among the modules that they control and are generally grouped together by module. Much of the SFR space contains unused addresses; these are read as '0'.

Note:	The actual set of peripheral features and interrupts varies by the device. Refer to the corresponding device tables and pinout diagrams for device-specific information.

4.2.4 NEAR DATA SPACE

The 8-Kbyte area, between 0x0000 and 0x1FFF, is referred to as the Near Data Space. Locations in this space are directly addressable through a 13-bit absolute address field within all memory direct instructions. Additionally, the whole Data Space is addressable using MOV instructions, which support Memory Direct Addressing mode with a 16-bit address field, or by using Indirect Addressing mode using a working register as an Address Pointer.

TABLE 4-49: PORTD REGISTER MAP FOR PIC24EPXXXGP/MC206 AND dsPIC33EPXXXGP/MC206/506 DEVICES ONLY

File Name	Addr.	Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	All Resets
TRISD	0E30	—	—	—	—	—	—	—	TRISD8	—	TRISD6	TRISD5	—	—	—	—	—	0160
PORTD	0E32	—	—	—	—	—	—	—	RD8	—	RD6	RD5	—	—	—	—	—	xxxx
LATD	0E34	—	—	—	—	—	—	—	LATD8	—	LATD6	LATD5	—	—	—	—	—	xxxx
ODCD	0E36	—	—	—	—	—	—	—	ODCD8	—	ODCD6	ODCD5	—	—	—	—	—	0000
CNEND	0E38	—	—	—	—	—	—	—	CNIED8	—	CNIED6	CNIED5	—	—	—	—	—	0000
CNPUD	0E3A	—	—	—	—	—	—	—	CNPUD8	—	CNPUD6	CNPUD5	—	—	—	—	—	0000
CNPDD	0E3C	—	—	—	—	—	—	—	CNPDD8	—	CNPDD6	CNPDD5	—	—	—	—	—	0000

Legend: x = unknown value on Reset, — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

TABLE 4-50: PORTE REGISTER MAP FOR PIC24EPXXXGP/MC206 AND dsPIC33EPXXXGP/MC206/506 DEVICES ONLY

File Name	Addr.	Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	All Resets
TRISE	0E40	TRISE15	TRISE14	TRISE13	TRISE12	—	—	—	—	—	—	—	—	—	—	—	—	F000
PORTE	0E42	RE15	RE14	RE13	RE12	—	—	—	—	—	—	—	—	—	—	—	—	xxxx
LATE	0E44	LATE15	LATE14	LATE13	LATE12	—	—	—	—	—	—	—	—	—	—	—	—	xxxx
ODCE	0E46	ODCE15	ODCE14	ODCE13	ODCE12	—	—	—	—	—	—	—	—	—	—	—	—	0000
CNENE	0E48	CNIEE15	CNIEE14	CNIEE13	CNIEE12	—	—	—	—	—	—	—	—	—	—	—	—	0000
CNPUE	0E4A	CNPUE15	CNPUE14	CNPUE13	CNPUE12	—	—	—	—	—	—	—	—	—	—	—	—	0000
CNPDE	0E4C	CNPDE15	CNPDE14	CNPDE13	CNPDE12	—	—	—	—	—	—	—	—	—	—	—	—	0000
ANSELE	0E4E	ANSE15	ANSE14	ANSE13	ANSE12	—	—	—	—	—	—	—	—	—	—	—	—	F000

Legend: x = unknown value on Reset, — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

TABLE 4-51: PORTF REGISTER MAP FOR PIC24EPXXXGP/MC206 AND dsPIC33EPXXXGP/MC206/506 DEVICES ONLY

File Name	Addr.	Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	All Resets
TRISF	0E50	—	—	—	—	—	—	—	—	—	—	—	—	—	—	TRISF1	TRISF0	0003
PORTF	0E52	—	—	—	—	—	—	—	—	—	—	—	—	—	—	RF1	RF0	xxxx
LATF	0E54	—	—	—	—	—	—	—	—	—	—	—	—	—	—	LATF1	LATF0	xxxx
ODCF	0E56	—	—	—	—	—	—	—	—	—	—	—	—	—	—	ODCF1	ODCF0	0000
CNENF	0E58	—	—	—	—	—	—	—	—	—	—	—	—	—	—	CNIEF1	CNIEF0	0000
CNPUF	0E5A	—	—	—	—	—	—	—	—	—	—	—	—	—	—	CNPUF1	CNPUF0	0000
CNPDF	0E5C	—	—	—	—	—	—	—	—	—	—	—	—	—	—	CNPDF1	CNPDF0	0000

Legend: x = unknown value on Reset, — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

4.6 Modulo Addressing (dsPIC33EPXXXMC20X/50X and dsPIC33EPXXXGP50X Devices Only)

Modulo Addressing mode is a method of providing an automated means to support circular data buffers using hardware. The objective is to remove the need for software to perform data address boundary checks when executing tightly looped code, as is typical in many DSP algorithms.

Modulo Addressing can operate in either Data or Program Space (since the Data Pointer mechanism is essentially the same for both). One circular buffer can be supported in each of the X (which also provides the pointers into Program Space) and Y Data Spaces. Modulo Addressing can operate on any W Register Pointer. However, it is not advisable to use W14 or W15 for Modulo Addressing since these two registers are used as the Stack Frame Pointer and Stack Pointer, respectively.

In general, any particular circular buffer can be configured to operate in only one direction, as there are certain restrictions on the buffer start address (for incrementing buffers) or end address (for decrementing buffers), based upon the direction of the buffer.

The only exception to the usage restrictions is for buffers that have a power-of-two length. As these buffers satisfy the start and end address criteria, they can operate in a bidirectional mode (that is, address boundary checks are performed on both the lower and upper address boundaries).

4.6.1 START AND END ADDRESS

The Modulo Addressing scheme requires that a starting and ending address be specified, and loaded into the 16-bit Modulo Buffer Address registers: XMODSRT, XMODEND, YMODSRT and YMODEND (see Table 4-1).

Note:	Y space Modulo Addressing EA calculations assume word-sized data (LSb of every EA is always clear).

The length of a circular buffer is not directly specified. It is determined by the difference between the corresponding start and end addresses. The maximum possible length of the circular buffer is 32K words (64 Kbytes).

4.6.2 W ADDRESS REGISTER SELECTION

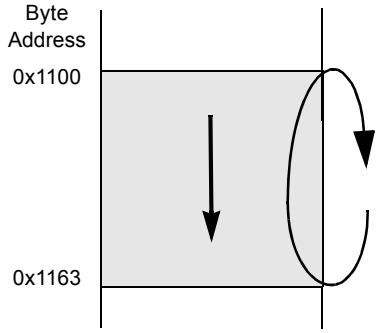
The Modulo and Bit-Reversed Addressing Control register, MODCON<15:0>, contains enable flags as well as a W register field to specify the W Address registers. The XWM and YWM fields select the registers that operate with Modulo Addressing:

- If XWM = 1111, X RAGU and X WAGU Modulo Addressing is disabled
- If YWM = 1111, Y AGU Modulo Addressing is disabled

The X Address Space Pointer W register (XWM), to which Modulo Addressing is to be applied, is stored in MODCON<3:0> (see Table 4-1). Modulo Addressing is enabled for X Data Space when XWM is set to any value other than '1111' and the XMODEN bit is set (MODCON<15>).

The Y Address Space Pointer W register (YWM), to which Modulo Addressing is to be applied, is stored in MODCON<7:4>. Modulo Addressing is enabled for Y Data Space when YWM is set to any value other than '1111' and the YMODEN bit is set at MODCON<14>.

FIGURE 4-20: MODULO ADDRESSING OPERATION EXAMPLE




```
MOV     #0x1100, W0
MOV     W0, XMODSRT     ;set modulo start address
MOV     #0x1163, W0
MOV     W0, MODEND      ;set modulo end address
MOV     #0x8001, W0
MOV     W0, MODCON      ;enable W1, X AGU for modulo

MOV     #0x0000, W0     ;W0 holds buffer fill value

MOV     #0x1110, W1     ;point W1 to buffer

DO      AGAIN, #0x31    ;fill the 50 buffer locations
MOV     W0, [W1++]      ;fill the next location
AGAIN:  INC W0, W0      ;increment the fill value
```

REGISTER 7-3: INTCON1: INTERRUPT CONTROL REGISTER 1 (CONTINUED)

bit 4 **MATHERR:** Math Error Status bit
1 = Math error trap has occurred
0 = Math error trap has not occurred

bit 3 **ADDRERR:** Address Error Trap Status bit
1 = Address error trap has occurred
0 = Address error trap has not occurred

bit 2 **STKERR:** Stack Error Trap Status bit
1 = Stack error trap has occurred
0 = Stack error trap has not occurred

bit 1 **OSCFAIL:** Oscillator Failure Trap Status bit
1 = Oscillator failure trap has occurred
0 = Oscillator failure trap has not occurred

bit 0 **Unimplemented:** Read as '0'

Note 1: These bits are available on dsPIC33EPXXXMC20X/50X and dsPIC33EPXXXGP50X devices only.

10.0 POWER-SAVING FEATURES

Note 1: This data sheet summarizes the features of the dsPIC33EPXXXGP50X, dsPIC33EPXXXMC20X/50X and PIC24EPXXXGP/MC20X families of devices. It is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to **"Watchdog Timer and Power-Saving Modes"** (DS70615) in the "*dsPIC33/PIC24 Family Reference Manual*", which is available from the Microchip web site (www.microchip.com).

2: Some registers and associated bits described in this section may not be available on all devices. Refer to **Section 4.0 "Memory Organization"** in this data sheet for device-specific register and bit information.

The dsPIC33EPXXXGP50X, dsPIC33EPXXXMC20X/50X and PIC24EPXXXGP/MC20X devices provide the ability to manage power consumption by selectively managing clocking to the CPU and the peripherals. In general, a lower clock frequency and a reduction in the number of peripherals being clocked constitutes lower consumed power.

dsPIC33EPXXXGP50X, dsPIC33EPXXXMC20X/50X and PIC24EPXXXGP/MC20X devices can manage power consumption in four ways:

- Clock Frequency
- Instruction-Based Sleep and Idle modes
- Software-Controlled Doze mode
- Selective Peripheral Control in Software

Combinations of these methods can be used to selectively tailor an application's power consumption while still maintaining critical application features, such as timing-sensitive communications.

10.1 Clock Frequency and Clock Switching

The dsPIC33EPXXXGP50X, dsPIC33EPXXXMC20X/50X and PIC24EPXXXGP/MC20X devices allow a wide range of clock frequencies to be selected under application control. If the system clock configuration is not locked, users can choose low-power or high-precision oscillators by simply changing the NOSCx bits (OSCCON<10:8>). The process of changing a system clock during operation, as well as limitations to the process, are discussed in more detail in **Section 9.0 "Oscillator Configuration"**.

10.2 Instruction-Based Power-Saving Modes

The dsPIC33EPXXXGP50X, dsPIC33EPXXXMC20X/50X and PIC24EPXXXGP/MC20X devices have two special power-saving modes that are entered through the execution of a special PWRSAV instruction. Sleep mode stops clock operation and halts all code execution. Idle mode halts the CPU and code execution, but allows peripheral modules to continue operation. The assembler syntax of the PWRSAV instruction is shown in Example 10-1.

Note: SLEEP_MODE and IDLE_MODE are constants defined in the assembler include file for the selected device.

Sleep and Idle modes can be exited as a result of an enabled interrupt, WDT time-out or a device Reset. When the device exits these modes, it is said to "wake-up".

EXAMPLE 10-1: PWRSAV INSTRUCTION SYNTAX

```
PWRSAV  #SLEEP_MODE    ; Put the device into Sleep mode
PWRSAV  #IDLE_MODE     ; Put the device into Idle mode
```

REGISTER 11-16: RPINR38: PERIPHERAL PIN SELECT INPUT REGISTER 38 (dsPIC33EPXXXMC20X AND PIC24EPXXXMC20X DEVICES ONLY)

U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
—	DTCMP1R<6:0>						
bit 15							bit 8

U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
—	—	—	—	—	—	—	—
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15 **Unimplemented:** Read as ‘0’

bit 14-8 **DTCMP1R<6:0>:** Assign PWM Dead-Time Compensation Input 1 to the Corresponding RPn Pin bits (see Table 11-2 for input pin selection numbers)

1111001 = Input tied to RPI121
.
.
.
0000001 = Input tied to CMP1
0000000 = Input tied to Vss

bit 7-0 **Unimplemented:** Read as ‘0’

12.2 Timer1 Control Register

REGISTER 12-1: T1CON: TIMER1 CONTROL REGISTER

R/W-0	U-0	R/W-0	U-0	U-0	U-0	U-0	U-0
TON(1)	—	TSIDL	—	—	—	—	—
bit 15							bit 8

U-0	R/W-0	R/W-0	R/W-0	U-0	R/W-0	R/W-0	U-0
—	TGATE	TCKPS1	TCKPS0	—	TSYNC(1)	TCS(1)	—
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15 **TON:** Timer1 On bit(1)
1 = Starts 16-bit Timer1
0 = Stops 16-bit Timer1

bit 14 **Unimplemented:** Read as '0'

bit 13 **TSIDL:** Timer1 Stop in Idle Mode bit
1 = Discontinues module operation when device enters Idle mode
0 = Continues module operation in Idle mode

bit 12-7 **Unimplemented:** Read as '0'

bit 6 **TGATE:** Timer1 Gated Time Accumulation Enable bit
When TCS = 1:
This bit is ignored.
When TCS = 0:
1 = Gated time accumulation is enabled
0 = Gated time accumulation is disabled

bit 5-4 **TCKPS<1:0>:** Timer1 Input Clock Prescale Select bits
11 = 1:256
10 = 1:64
01 = 1:8
00 = 1:1

bit 3 **Unimplemented:** Read as '0'

bit 2 **TSYNC:** Timer1 External Clock Input Synchronization Select bit(1)
When TCS = 1:
1 = Synchronizes external clock input
0 = Does not synchronize external clock input
When TCS = 0:
This bit is ignored.

bit 1 **TCS:** Timer1 Clock Source Select bit(1)
1 = External clock is from pin, T1CK (on the rising edge)
0 = Internal clock (FP)

bit 0 **Unimplemented:** Read as '0'

Note 1: When Timer1 is enabled in External Synchronous Counter mode (TCS = 1, TSYNC = 1, TON = 1), any attempts by user software to write to the TMR1 register are ignored.

13.0 TIMER2/3 AND TIMER4/5

Note 1: This data sheet summarizes the features of the dsPIC33EPXXXGP50X, dsPIC33EPXXXMC20X/50X and PIC24EPXXXGP/MC20X family of devices. It is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to **"Timers"** (DS70362) of the *"dsPIC33/PIC24 Family Reference Manual"*, which is available from the Microchip web site (www.microchip.com).

2: Some registers and associated bits described in this section may not be available on all devices. Refer to **Section 4.0 "Memory Organization"** in this data sheet for device-specific register and bit information.

The Timer2/3 and Timer4/5 modules are 32-bit timers, which can also be configured as four independent 16-bit timers with selectable operating modes.

As 32-bit timers, Timer2/3 and Timer4/5 operate in three modes:

- Two Independent 16-Bit Timers (e.g., Timer2 and Timer3) with all 16-Bit Operating modes (except Asynchronous Counter mode)
- Single 32-Bit Timer
- Single 32-Bit Synchronous Counter

They also support these features:

- Timer Gate Operation
- Selectable Prescaler Settings
- Timer Operation during Idle and Sleep modes
- Interrupt on a 32-Bit Period Register Match
- Time Base for Input Capture and Output Compare Modules (Timer2 and Timer3 only)
- ADC1 Event Trigger (32-bit timer pairs, and Timer3 and Timer5 only)

Individually, all four of the 16-bit timers can function as synchronous timers or counters. They also offer the features listed previously, except for the event trigger; this is implemented only with Timer2/3. The operating modes and enabled features are determined by setting the appropriate bit(s) in the T2CON, T3CON, and T4CON, T5CON registers. T2CON and T4CON are shown in generic form in Register 13-1. T3CON and T5CON are shown in Register 13-2.

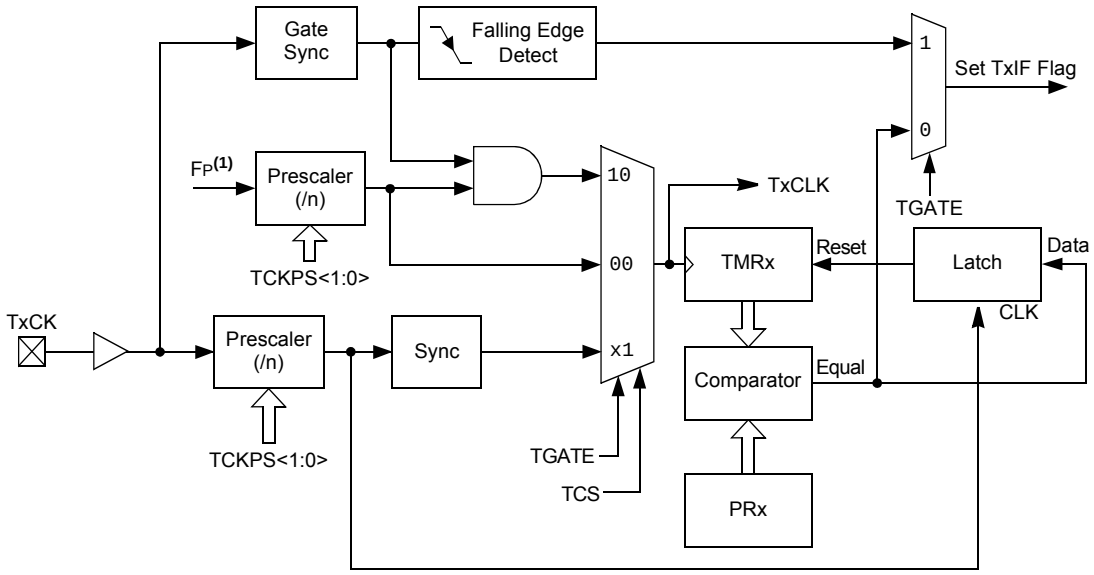
For 32-bit timer/counter operation, Timer2 and Timer4 are the least significant word (lsw); Timer3 and Timer5 are the most significant word (msw) of the 32-bit timers.

Note: For 32-bit operation, T3CON and T5CON control bits are ignored. Only T2CON and T4CON control bits are used for setup and control. Timer2 and Timer4 clock and gate inputs are utilized for the 32-bit timer modules, but an interrupt is generated with the Timer3 and Timer5 interrupt flags.

A block diagram for an example 32-bit timer pair (Timer2/3 and Timer4/5) is shown in Figure 13-3.

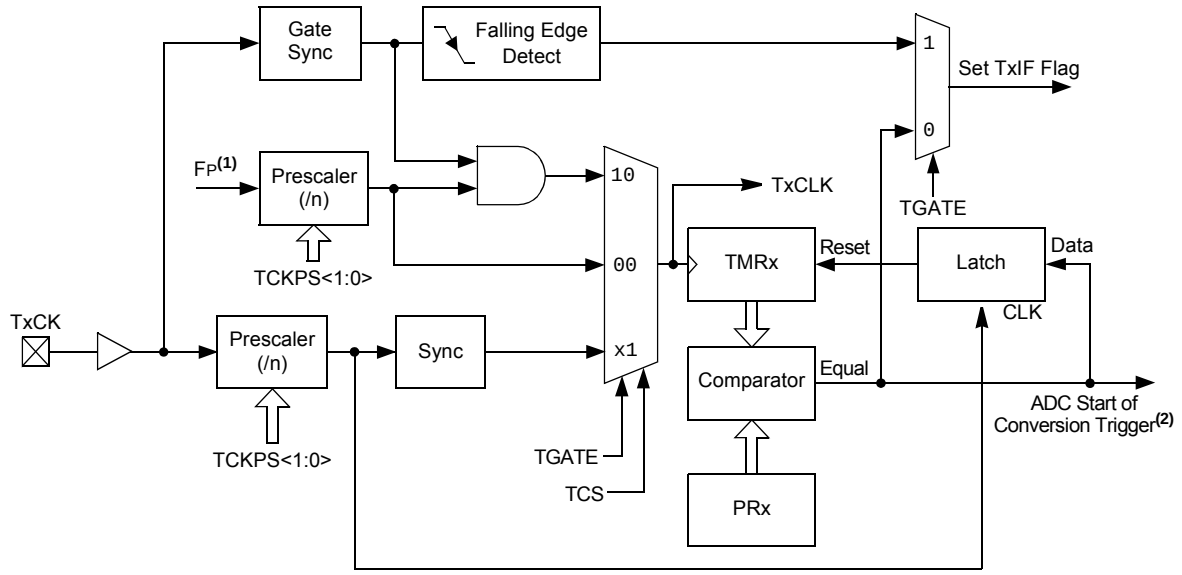
Note: Only Timer2, 3, 4 and 5 can trigger a DMA data transfer.

FIGURE 13-1: TYPE B TIMER BLOCK DIAGRAM (x = 2 AND 4)



Note 1: FP is the peripheral clock.

FIGURE 13-2: TYPE C TIMER BLOCK DIAGRAM (x = 3 AND 5)



Note 1: FP is the peripheral clock.
2: The ADC trigger is available on TMR3 and TMR5 only.

REGISTER 15-1: OCxCON1: OUTPUT COMPARE x CONTROL REGISTER 1 (CONTINUED)

bit 3 **TRIGMODE:** Trigger Status Mode Select bit
- 1 = TRIGSTAT (OCxCON2<6>) is cleared when OCxRS = OCxTMR or in software
- 0 = TRIGSTAT is cleared only by software

bit 2-0 **OCM<2:0>:** Output Compare x Mode Select bits
- 111 = Center-Aligned PWM mode: Output set high when OCxTMR = OCxR and set low when OCxTMR = OCxRS(1)
- 110 = Edge-Aligned PWM mode: Output set high when OCxTMR = 0 and set low when OCxTMR = OCxR(1)
- 101 = Double Compare Continuous Pulse mode: Initializes OCx pin low, toggles OCx state continuously on alternate matches of OCxR and OCxRS
- 100 = Double Compare Single-Shot mode: Initializes OCx pin low, toggles OCx state on matches of OCxR and OCxRS for one cycle
- 011 = Single Compare mode: Compare event with OCxR, continuously toggles OCx pin
- 010 = Single Compare Single-Shot mode: Initializes OCx pin high, compare event with OCxR, forces OCx pin low
- 001 = Single Compare Single-Shot mode: Initializes OCx pin low, compare event with OCxR, forces OCx pin high
- 000 = Output compare channel is disabled

Note 1: OCxR and OCxRS are double-buffered in PWM mode only.

2: Each Output Compare x module (OCx) has one PTG clock source. See **Section 24.0 “Peripheral Trigger Generator (PTG) Module”** for more information.
PTGO4 = OC1
PTGO5 = OC2
PTGO6 = OC3
PTGO7 = OC4

REGISTER 16-16: LEBCONx: PWMx LEADING-EDGE BLANKING CONTROL REGISTER

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	U-0	U-0
PHR	PHF	PLR	PLF	FLTLEBEN	CLLEBEN	—	—
bit 15							bit 8

U-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
—	—	BCH(1)	BCL(1)	BPHH	BPHL	BPLH	BPLL
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15 **PHR:** PWMxH Rising Edge Trigger Enable bit
1 = Rising edge of PWMxH will trigger Leading-Edge Blanking counter
0 = Leading-Edge Blanking ignores rising edge of PWMxH

bit 14 **PHF:** PWMxH Falling Edge Trigger Enable bit
1 = Falling edge of PWMxH will trigger Leading-Edge Blanking counter
0 = Leading-Edge Blanking ignores falling edge of PWMxH

bit 13 **PLR:** PWMxL Rising Edge Trigger Enable bit
1 = Rising edge of PWMxL will trigger Leading-Edge Blanking counter
0 = Leading-Edge Blanking ignores rising edge of PWMxL

bit 12 **PLF:** PWMxL Falling Edge Trigger Enable bit
1 = Falling edge of PWMxL will trigger Leading-Edge Blanking counter
0 = Leading-Edge Blanking ignores falling edge of PWMxL

bit 11 **FLTLEBEN:** Fault Input Leading-Edge Blanking Enable bit
1 = Leading-Edge Blanking is applied to selected Fault input
0 = Leading-Edge Blanking is not applied to selected Fault input

bit 10 **CLLEBEN:** Current-Limit Leading-Edge Blanking Enable bit
1 = Leading-Edge Blanking is applied to selected current-limit input
0 = Leading-Edge Blanking is not applied to selected current-limit input

bit 9-6 **Unimplemented:** Read as '0'

bit 5 **BCH:** Blanking in Selected Blanking Signal High Enable bit(1)
1 = State blanking (of current-limit and/or Fault input signals) when selected blanking signal is high
0 = No blanking when selected blanking signal is high

bit 4 **BCL:** Blanking in Selected Blanking Signal Low Enable bit(1)
1 = State blanking (of current-limit and/or Fault input signals) when selected blanking signal is low
0 = No blanking when selected blanking signal is low

bit 3 **BPHH:** Blanking in PWMxH High Enable bit
1 = State blanking (of current-limit and/or Fault input signals) when PWMxH output is high
0 = No blanking when PWMxH output is high

bit 2 **BPHL:** Blanking in PWMxH Low Enable bit
1 = State blanking (of current-limit and/or Fault input signals) when PWMxH output is low
0 = No blanking when PWMxH output is low

bit 1 **BPLH:** Blanking in PWMxL High Enable bit
1 = State blanking (of current-limit and/or Fault input signals) when PWMxL output is high
0 = No blanking when PWMxL output is high

bit 0 **BPLL:** Blanking in PWMxL Low Enable bit
1 = State blanking (of current-limit and/or Fault input signals) when PWMxL output is low
0 = No blanking when PWMxL output is low

Note 1: The blanking signal is selected via the BLANKSELx bits in the AUXCONx register.

REGISTER 17-2: QEI1IOC: QEI1 I/O CONTROL REGISTER

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
QCAPEN	FLTREN	QFDIV2	QFDIV1	QFDIV0	OUTFNC1	OUTFNC0	SWPAB
bit 15							bit 8

R/W-0	R/W-0	R/W-0	R/W-0	R-x	R-x	R-x	R-x
HOMPOL	IDXPOL	QEBPOL	QEAPOL	HOME	INDEX	QEB	QEA
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15 **QCAPEN:** QEI Position Counter Input Capture Enable bit
1 = Index match event triggers a position capture event
0 = Index match event does not trigger a position capture event

bit 14 **FLTREN:** QEAx/QEBx/INDXx/HOMEx Digital Filter Enable bit
1 = Input pin digital filter is enabled
0 = Input pin digital filter is disabled (bypassed)

bit 13-11 **QFDIV<2:0>:** QEAx/QEBx/INDXx/HOMEx Digital Input Filter Clock Divide Select bits
111 = 1:128 clock divide
110 = 1:64 clock divide
101 = 1:32 clock divide
100 = 1:16 clock divide
011 = 1:8 clock divide
010 = 1:4 clock divide
001 = 1:2 clock divide
000 = 1:1 clock divide

bit 10-9 **OUTFNC<1:0>:** QEI Module Output Function Mode Select bits
11 = The CTNCMPx pin goes high when QEI1LEC ≥ POS1CNT ≥ QEI1GEC
10 = The CTNCMPx pin goes high when POS1CNT ≤ QEI1LEC
01 = The CTNCMPx pin goes high when POS1CNT ≥ QEI1GEC
00 = Output is disabled

bit 8 **SWPAB:** Swap QEA and QEB Inputs bit
1 = QEAx and QEBx are swapped prior to quadrature decoder logic
0 = QEAx and QEBx are not swapped

bit 7 **HOMPOL:** HOMEx Input Polarity Select bit
1 = Input is inverted
0 = Input is not inverted

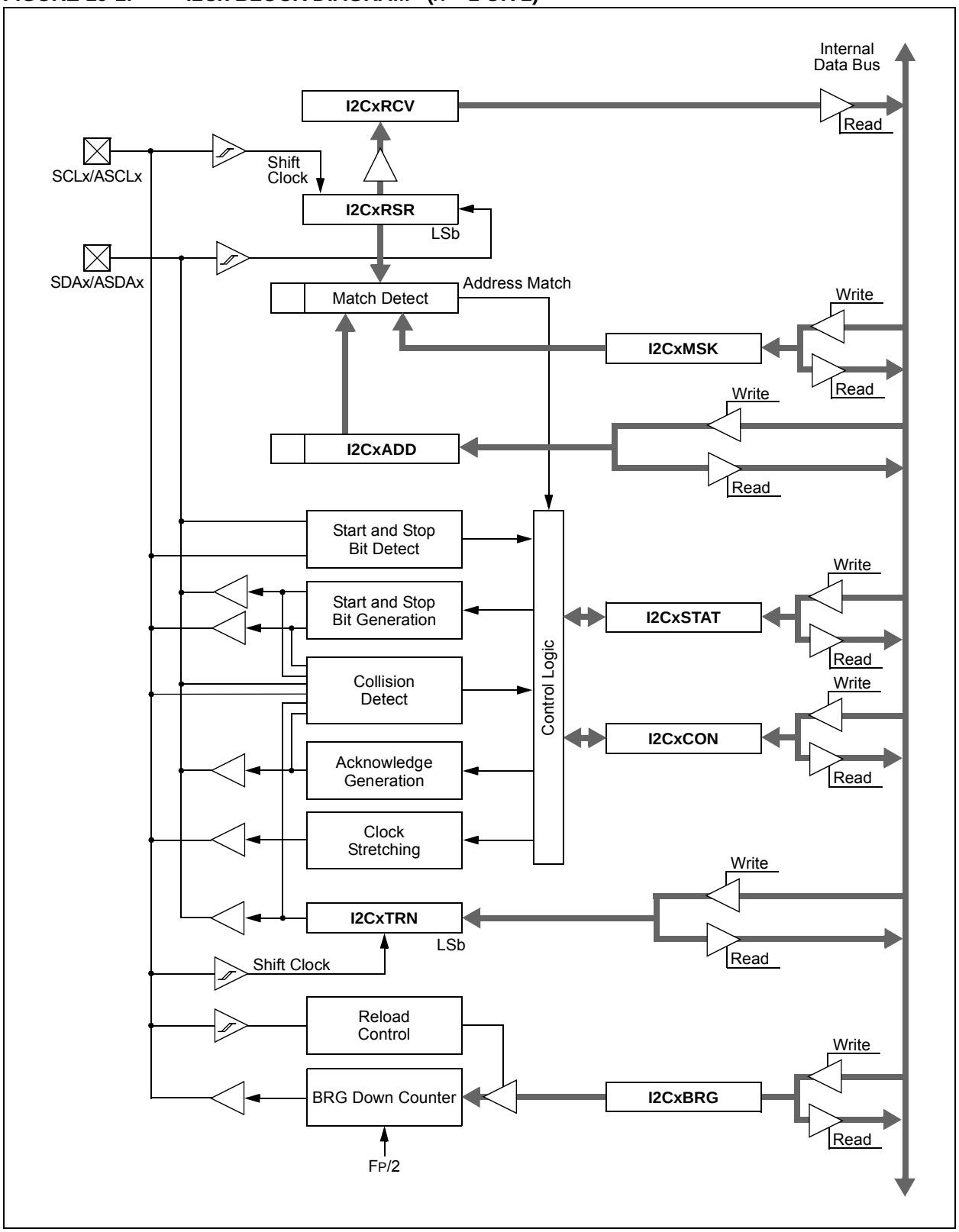
bit 6 **IDXPOL:** INDXx Input Polarity Select bit
1 = Input is inverted
0 = Input is not inverted

bit 5 **QEBPOL:** QEBx Input Polarity Select bit
1 = Input is inverted
0 = Input is not inverted

bit 4 **QEAPOL:** QEAx Input Polarity Select bit
1 = Input is inverted
0 = Input is not inverted

bit 3 **HOME:** Status of HOMEx Input Pin After Polarity Control
1 = Pin is at logic '1'
0 = Pin is at logic '0'

FIGURE 19-1: I2Cx BLOCK DIAGRAM (x = 1 OR 2)



27.5 Watchdog Timer (WDT)

For dsPIC33EPXXXGP50X, dsPIC33EPXXXMC20X/50X and PIC24EPXXXGP/MC20X devices, the WDT is driven by the LPRC oscillator. When the WDT is enabled, the clock source is also enabled.

27.5.1 PRESCALER/POSTSCALER

The nominal WDT clock source from LPRC is 32 kHz. This feeds a prescaler that can be configured for either 5-bit (divide-by-32) or 7-bit (divide-by-128) operation. The prescaler is set by the WDTPRE Configuration bit. With a 32 kHz input, the prescaler yields a WDT Time-out period (TWDT), as shown in Parameter SY12 in Table 30-22.

A variable postscaler divides down the WDT prescaler output and allows for a wide range of time-out periods. The postscaler is controlled by the WDTPOST<3:0> Configuration bits (FWDT<3:0>), which allow the selection of 16 settings, from 1:1 to 1:32,768. Using the prescaler and postscaler, time-out periods ranging from 1 ms to 131 seconds can be achieved.

The WDT, prescaler and postscaler are reset:

- On any device Reset
- On the completion of a clock switch, whether invoked by software (i.e., setting the OSWEN bit after changing the NOSCx bits) or by hardware (i.e., Fail-Safe Clock Monitor)
- When a PWRSAV instruction is executed (i.e., Sleep or Idle mode is entered)
- When the device exits Sleep or Idle mode to resume normal operation
- By a CLRWDT instruction during normal execution

Note: The CLRWDT and PWRSAV instructions clear the prescaler and postscaler counts when executed.

27.5.2 SLEEP AND IDLE MODES

If the WDT is enabled, it continues to run during Sleep or Idle modes. When the WDT time-out occurs, the device wakes the device and code execution continues from where the PWRSAV instruction was executed. The corresponding SLEEP or IDLE bit (RCON<3,2>) needs to be cleared in software after the device wakes up.

27.5.3 ENABLING WDT

The WDT is enabled or disabled by the FWDTEN Configuration bit in the FWDT Configuration register. When the FWDTEN Configuration bit is set, the WDT is always enabled.

The WDT can be optionally controlled in software when the FWDTEN Configuration bit has been programmed to '0'. The WDT is enabled in software by setting the SWDTEN control bit (RCON<5>). The SWDTEN control bit is cleared on any device Reset. The software WDT option allows the user application to enable the WDT for critical code segments and disable the WDT during non-critical segments for maximum power savings.

The WDT flag bit, WDTO (RCON<4>), is not automatically cleared following a WDT time-out. To detect subsequent WDT events, the flag must be cleared in software.

27.5.4 WDT WINDOW

The Watchdog Timer has an optional Windowed mode, enabled by programming the WINDIS bit in the WDT Configuration register (FWDT<6>). In the Windowed mode (WINDIS = 0), the WDT should be cleared based on the settings in the programmable Watchdog Timer Window select bits (WDTWIN<1:0>).

FIGURE 27-2: WDT BLOCK DIAGRAM

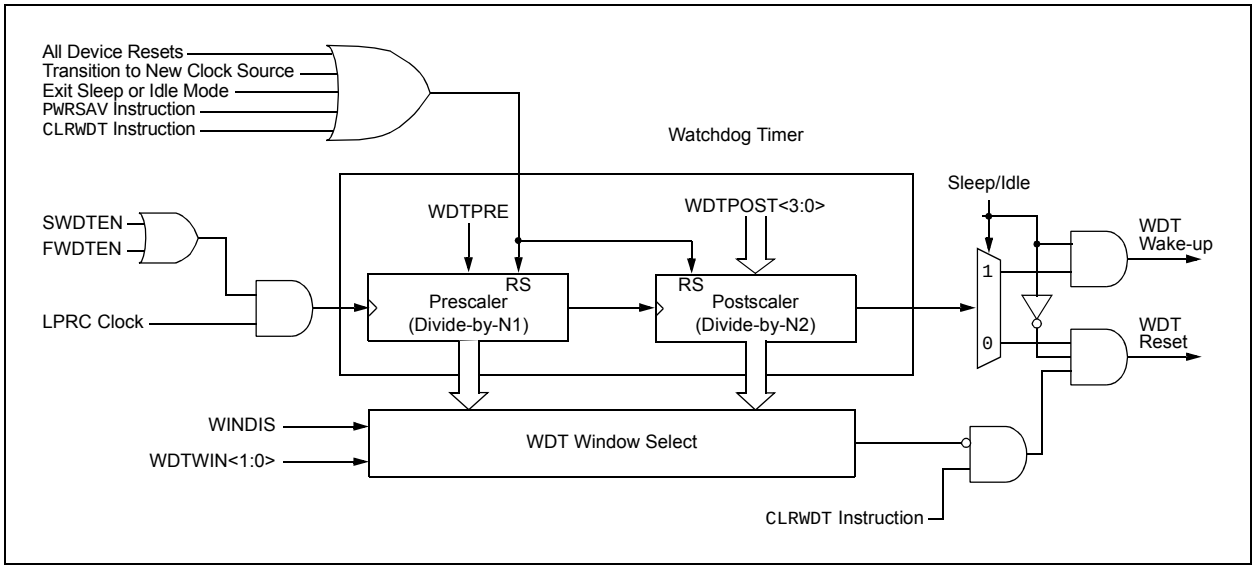


FIGURE 30-28: SPI1 SLAVE MODE (FULL-DUPLEX, CKE = 0, CKP = 1, SMP = 0) TIMING CHARACTERISTICS

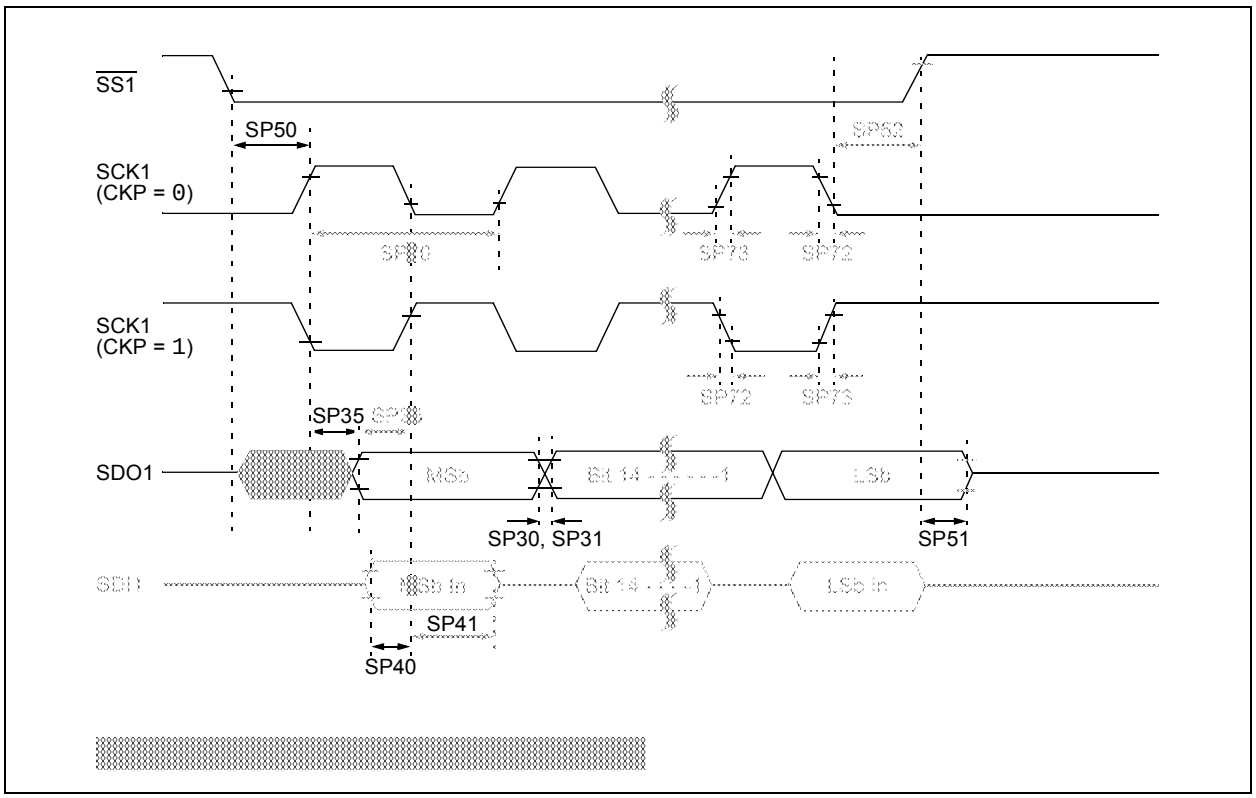


TABLE 31-4: DC CHARACTERISTICS: POWER-DOWN CURRENT (I_{PD})

DC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +150°C			
Parameter No.	Typical	Max	Units	Conditions		
Power-Down Current (I_{PD})						
HDC60e	1400	2500	μA	+150°C	3.3V	Base Power-Down Current **(Notes 1, 3)**
HDC61c	15	—	μA	+150°C	3.3V	Watchdog Timer Current: ΔI_{WDT} **(Notes 2, 4)**

Note 1: Base I_{PD} is measured with all peripherals and clocks shut down. All I/Os are configured as inputs and pulled to V_{SS}. WDT, etc., are all switched off and VREGS (RCON<8>) = 1.

2: The Δ current is the additional current consumed when the module is enabled. This current should be added to the base I_{PD} current.

3: These currents are measured on the device containing the most memory in this family.

4: These parameters are characterized, but are not tested in manufacturing.

TABLE 31-5: DC CHARACTERISTICS: IDLE CURRENT (I_{IDLE})

DC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +150°C			
Parameter No.	Typical	Max	Units	Conditions		
HDC44e	12	30	mA	+150°C	3.3V	40 MIPS

TABLE 31-6: DC CHARACTERISTICS: OPERATING CURRENT (I_{DD})

DC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +150°C			
Parameter No.	Typical	Max	Units	Conditions		
HDC20	9	15	mA	+150°C	3.3V	10 MIPS
HDC22	16	25	mA	+150°C	3.3V	20 MIPS
HDC23	30	50	mA	+150°C	3.3V	40 MIPS

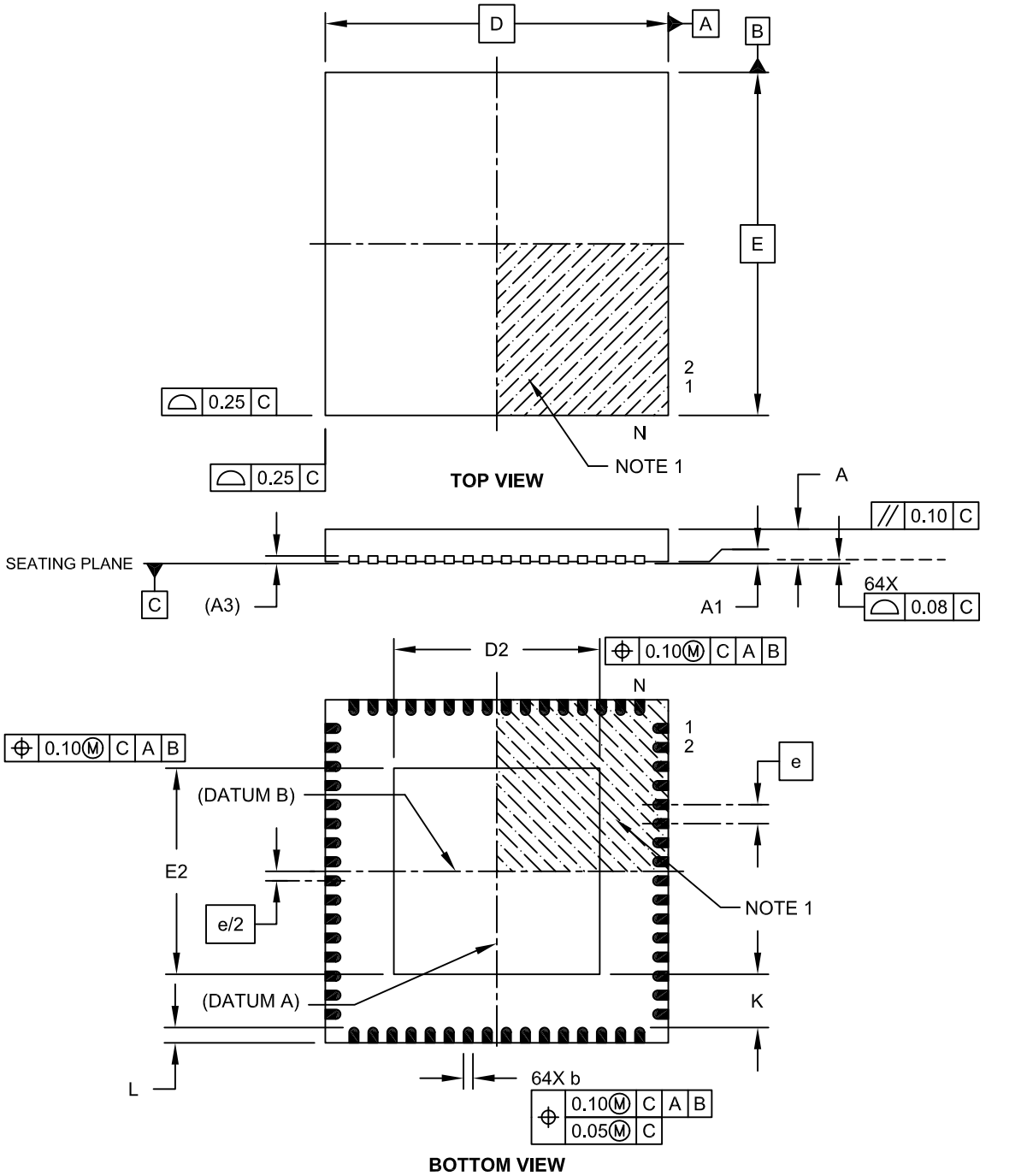
TABLE 31-7: DC CHARACTERISTICS: DOZE CURRENT (I_{DOZE})

DC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +150°C				
Parameter No.	Typical	Max	Doze Ratio	Units	Conditions		
HDC72a	24	35	1:2	mA	+150°C	3.3V	40 MIPS
HDC72f(1)	14	—	1:64	mA			
HDC72g(1)	12	—	1:128	mA			

Note 1: Parameters with Doze ratios of 1:64 and 1:128 are characterized, but are not tested in manufacturing.

64-Lead Plastic Quad Flat, No Lead Package (MR) – 9x9x0.9 mm Body with 5.40 x 5.40 Exposed Pad [QFN]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



Microchip Technology Drawing C04-154A Sheet 1 of 2

Revision D (December 2011)

This revision includes typographical and formatting changes throughout the data sheet text.

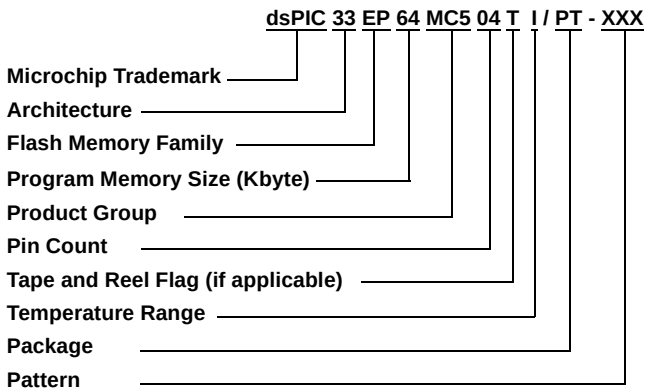
All other major changes are referenced by their respective section in Table A-3.

TABLE A-3: MAJOR SECTION UPDATES

Section Name	Update Description
"16-bit Microcontrollers and Digital Signal Controllers (up to 512-Kbyte Flash and 48-Kbyte SRAM) with High-Speed PWM, Op amps, and Advanced Analog"	Removed the Analog Comparators column and updated the Op amps/Comparators column in Table 1 and Table 2.
Section 21.0 "Enhanced CAN (ECAN™) Module (dsPIC33EPXXXGP/MC50X Devices Only)"	Updated the CANCKS bit value definitions in CiCTRL1: ECAN Control Register 1 (see Register 21-1).
Section 30.0 "Electrical Characteristics"	Updated the V_{BOR} specifications and/or its related note in the following electrical characteristics tables: • Table 30-1 • Table 30-4 • Table 30-12 • Table 30-14 • Table 30-15 • Table 30-16 • Table 30-56 • Table 30-57 • Table 30-58 • Table 30-59 • Table 30-60

PRODUCT IDENTIFICATION SYSTEM

To order or obtain information, e.g., on pricing or delivery, refer to the factory or the listed sales office.



Examples:

dsPIC33EP64MC504-I/PT:
dsPIC33, Enhanced Performance,
64-Kbyte Program Memory,
Motor Control, 44-Pin,
Industrial Temperature,
TQFP package.

Architecture:	33	=	16-bit Digital Signal Controller
	24	=	16-bit Microcontroller
Flash Memory Family:	EP	=	Enhanced Performance
Product Group:	GP	=	General Purpose family
	MC	=	Motor Control family
Pin Count:	02	=	28-pin
	03	=	36-pin
	04	=	44-pin
	06	=	64-pin
Temperature Range:	I	=	-40°C to+85°C (Industrial)
	E	=	-40°C to+125°C (Extended)
Package:	ML	=	Plastic Quad, No Lead Package - (44-pin) 8x8 mm body (QFN)
	MM	=	Plastic Quad, No Lead Package - (28-pin) 6x6 mm body (QFN-S)
	MR	=	Plastic Quad, No Lead Package - (64-pin) 9x9 mm body (QFN)
	MV	=	Thin Quad, No Lead Package - (48-pin) 6x6 mm body (UQFN)
	PT	=	Plastic Thin Quad Flatpack - (44-pin) 10x10 mm body (TQFP)
	PT	=	Plastic Thin Quad Flatpack - (64-pin) 10x10 mm body (TQFP)
	SO	=	Plastic Small Outline, Wide - (28-pin) 7.50 mm body (SOIC)
	SP	=	Skinny Plastic Dual In-Line - (28-pin) 300 mil body (SPDIP)
	SS	=	Plastic Shrink Small Outline - (28-pin) 5.30 mm body (SSOP)
	TL	=	Very Thin Leadless Array - (36-pin) 5x5 mm body (VTLA)
	TL	=	Very Thin Leadless Array - (44-pin) 6x6 mm body (VTLA)